

M5M416165DJ,TP-5,-6,-7,-5S,-6S,-7S

EDO (HYPER PAGE) MODE 1677216-BIT (1048576-WORD BY 16-BIT) DYNAMIC RAM

DESCRIPTION

This is a family of 1048576-word by 16-bit dynamic RAMS with EDO(Extended Data Out : Hyper Page) mode function, fabricated with the high performance CMOS process, and is ideal for large-capacity memory systems where high speed, low power dissipation, and low costs are essential.

The use of double-layer metal process combined with twin-well CMOS technology and a single-transistor dynamic storage stacked capacitor cell provide high circuit density at reduced costs. Multiplexed address inputs permit both a reduction in pins and an increase in system densities. Self refresh current is low enough for battery back-up application.

FEATURES

Type name	RAS access time (max.ns)	CAS access time (max.ns)	Address access time (max.ns)	OE access time (max.ns)	Cycle time (min.ns)	Power dissipation (typ.mW)
M5M416165DXX-5,5S	50	13	25	13	90	540
M5M416165DXX-6,6S	60	15	30	15	110	430
M5M416165DXX-7,7S	70	20	35	20	130	385

XX=J,TP

- Standard 42 pin SOJ, 50 pin TSOP
 - Single 5.0V ±10% supply
 - Low stand-by power dissipation
5.5mW (Max) ----- CMOS Input level
 - Low operating power dissipation
M5M416165Dxx- 5,5S ----- 660.0mW (Max)
M5M416165Dxx- 6,6S ----- 525.0mW (Max)
M5M416165Dxx- 7,7S ----- 470.0mW (Max)
 - EDO mode, Read-modify-write, RAS-only refresh
CAS before RAS refresh, Hidden refresh capabilities
 - Early-write mode, W and OE to control output buffer impedance
 - All inputs, output TTL compatible and low capacitance
4096 refresh cycles every 64ms (A₀ - A₁₁)
4096 refresh cycles every 128ms (A₀ ~ A₁₁) *
- * : Applicable to self refresh version
(M5M416165DXX-5S,-6S,-7S:option) only

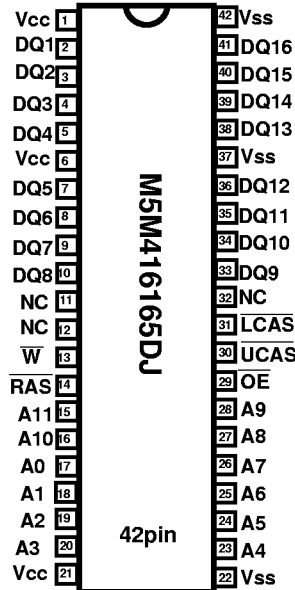
APPLICATION

Main memory unit for computers, Microcomputer memory, Refresh memory for CRT

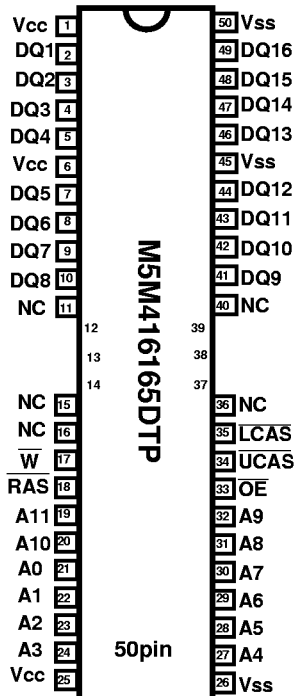
PIN DESCRIPTION

Pin Name	Function
A ₀ -A ₁₁	Address Inputs
DQ ₁ -DQ ₁₆	Data Inputs / Outputs
RAS	Row Address Strobe Input
UCAS	Upper Byte Control Column Address Strobe Input
LCAS	Lower Byte Control Column Address Strobe Input
W	Write Control Input
OE	Output Enable Input
Vcc	Power Supply (+5.0V)
Vss	Ground (0V)

PIN CONFIGURATION (TOP VIEW)



Outline 42P0N-A (400mil SOJ)



Outline 50P3G-F (400mil TSOP Normal Bend)

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FUNCTION

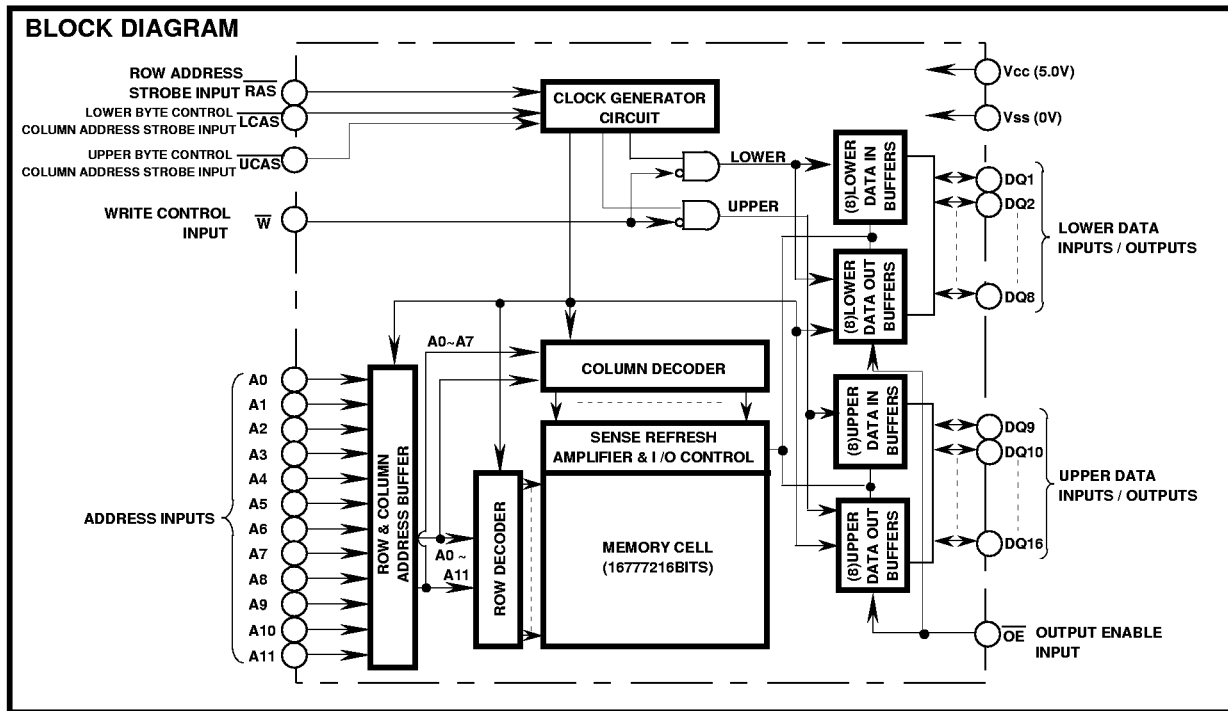
The M5M416165DJ, TP provide, in addition to normal read, write, and read-modify-write operations,

a number of other functions, e.g., EDO mode, RAS only refresh, and delayed-write. The input conditions for each are shown in Table 1.

Table 1 Input conditions for each mode

Operation	Inputs					Input/Output		Refresh	Remark
	RAS	LCAS	UCAS	W	OE	DQ1~DQ8	DQ9~DQ16		
Lower byte Read	ACT	ACT	NAC	NAC	ACT	VLD	OPN	YES	EDO mode identical
Upper byte Read	ACT	NAC	ACT	NAC	ACT	OPN	VLD	YES	
Word Read	ACT	ACT	ACT	NAC	ACT	VLD	VLD	YES	
Lower Byte Write	ACT	ACT	NAC	ACT	NAC	DIN	DNC	YES	
Upper Byte Write	ACT	NAC	ACT	ACT	NAC	DNC	DIN	YES	
Word write	ACT	ACT	ACT	ACT	NAC	DIN	DIN	YES	
RAS-only refresh	ACT	NAC	NAC	DNC	DNC	OPN	OPN	YES	
Hidden refresh	ACT	ACT	ACT	NAC	ACT	VLD	VLD	YES	
Self refresh	ACT	ACT	ACT	NAC	DNC	OPN	OPN	YES	
CAS before RAS refresh	ACT	ACT	ACT	DNC	DNC	OPN	OPN	YES	
Standby	NAC	DNC	DNC	DNC	DNC	OPN	OPN	NO	

Note : ACT : active, NAC : nonactive, DNC : don't care, VLD : valid, IVD : Invalid, APD : applied, OPN : open



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ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Conditions	Ratings	Unit
V _{cc}	Supply voltage	With respect to V _{ss}	-1 ~ 7	V
V _i	Input voltage		-1 ~ 7	V
V _o	Output voltage		-1 ~ 7	V
I _o	Output current		50	mA
P _d	Power dissipation	T _a =25°C	1000	mW
T _{opr}	Operating temperature		0 ~ 70	°C
T _{stg}	Storage temperature		-65 ~ 150	°C

RECOMMENDED OPERATING CONDITIONS (T_a=0 ~ 70°C, unless otherwise noted) (Note 1)

Symbol	Parameter	Limits			Unit
		Min	Nom	Max	
V _{cc}	Supply voltage	4.5	5.0	5.5	V
V _{ss}	Supply voltage	0	0	0	V
V _{IH}	High-level input voltage, all inputs	2.4		5.5	V
V _{IL}	Low-level input voltage, all inputs	-1.0**		0.8	V

Note 1 : All voltage values are with respect to V_{ss}** : V_{IL}(Min) is -2.0V when undershoot width is less than 25ns.(The width is defined as the period when the voltage level is below V_{ss}.)

ELECTRICAL CHARACTERISTICS (T_a=0 ~ 70°C, V_{cc}=5.0V±10%, V_{ss}=0V, unless otherwise noted) (Note 2)

Symbol	Parameter	Test conditions	Limits			Unit
			Min	Typ	Max	
V _{OH}	High-level output voltage	I _{OH} =5.0mA	2.4		V _{cc}	V
V _{OL}	Low-level output voltage	I _{OL} =4.2mA	0		0.4	V
I _{oz}	Off-state output current	Q floating 0V ≤ V _{OUT} ≤ 5.5V	-10		10	μA
I _I	Input current	0V ≤ V _{IN} ≤ 5.5V, Other inputs pins=0V	-10		10	μA
I _{cc1} (AV)	Average supply current from V _{cc} operating (Note 3,4,5)	M5M416165D-5,5S	RAS, CAS cycling trc=twc=min. output open		120	mA
		M5M416165D-6,6S			95	
		M5M416165D-7,7S			85	
I _{cc2}	Supply current from V _{cc} , stand-by (Note 6)	RAS= CAS=V _{IH} , output open		2	mA	
		RAS= CAS ≥ V _{cc} -0.2 V output open		1		
				0.3*		
I _{cc3} (AV)	Average supply current from V _{cc} refreshing (Note 3,5)	M5M416165D-5,5S	RAS cycling, CAS=V _{IH} trc=min. output open		120	mA
		M5M416165D-6,6S			95	
		M5M416165D-7,7S			85	
I _{cc4} (AV)	Average supply current from V _{cc} EDO-Mode (Note 3,4,5)	M5M416165D-5,5S	RAS=V _{IL} , CAS cycling tpc=min. output open		165	mA
		M5M416165D-6,6S			130	
		M5M416165D-7,7S			110	
I _{cc6} (AV)	Average supply current from V _{cc} CAS before RAS refresh mode (Note 3)	M5M416165D-5,5S	CAS before RAS refresh cycling trc=min. output open		120	mA
		M5M416165D-6,6S			95	
		M5M416165D-7,7S			85	
I _{cc8} (AV)*	Average supply current from V _{cc} Extended - Refresh cycle (Note 6)	M5M416165D (S)	Stand-by: RAS ≥ V _{cc} -0.2V CAS ≥ V _{cc} -0.2V or CAS ≤ 0.2V CAS before RAS refresh: RAS cycling CAS ≤ 0.2V or CAS before RAS refresh cycling W ≤ 0.2V or ≥ V _{cc} -0.2V OE ≤ 0.2V or ≥ V _{cc} -0.2V A0 ~ A9 ≤ 0.2V or ≥ V _{cc} -0.2V DQ=open, TRC=125μs, TRAS=TRASmin. ~ 1μs		600	μA
I _{cc9} (AV)*	Average supply current from V _{cc} Self - Refresh cycle	M5M416165D (S)	RAS = CAS ≤ 0.2V		400	μA

* : Applicable to self refresh version (M5M416165DXX-5S,-6S,-7S:option) only

Note 2 : Current flowing into an IC is positive, out is negative.

3: I_{cc1} (AV), I_{cc3} (AV) and I_{cc4} (AV) are dependent on cycle rate. Maximum current is measured at the fastest cycle rate.4: I_{cc1} (AV) and I_{cc4} (AV) are dependent on output loading. Specified values are obtained with the output open.5: Column Address can be changed once or less while RAS=V_{IL} and LCAS/UCAS=V_{IH}.

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CAPACITANCE (Ta=0 ~ 70°C, Vcc=5.0V ± 10%, Vss=0V, unless otherwise noted)

Symbol	Parameter		Test conditions	Limits			Unit
				Min	Typ	Max	
C _{i(A)}	Input capacitance, address inputs	M5M416165DJ, TP	V _i =V _{ss} f=1MHz V _i =25mVrms			5	pF
C _{i(OE)}	Input capacitance, \overline{OE} input					7	pF
C _{i(W)}	Input capacitance, write control input					7	pF
C _{i(RAS)}	Input capacitance, \overline{RAS} input					7	pF
C _{i(CAS)}	Input capacitance, CAS input					7	pF
C _{i/O}	Input/Output capacitance, data ports					7	pF

SWITCHING CHARACTERISTICS (Ta=0 ~ 70°C, Vcc = 5.0V ± 10%, Vss=0V, unless otherwise noted, see notes 6,14,15)

Symbol	Parameter	Limits						Unit
		M5M416165D-5,5S		M5M416165D-6,6S		M5M416165D-7,7S		
		Min	Max	Min	Max	Min	Max	
t _{CAC}	Access time from CAS (Note 7,8)		13		15		20	ns
t _{RAC}	Access time from RAS (Note 7,9)		50		60		70	ns
t _{AA}	Column address access time (Note 7,10)		25		30		35	ns
t _{CPA}	Access time from CAS precharge (Note 7,11)		30		35		40	ns
t _{OE}	Access time from \overline{OE} (Note 7)		13		15		20	ns
t _{OHC}	Output hold time from CAS	5		5		5		ns
t _{OHR}	Output hold time from RAS (Note 13)	5		5		5		ns
t _{CLZ}	Output low impedance time from \overline{CAS} low (Note 7)	5		5		5		ns
t _{OEZ}	Output disable time after \overline{OE} high (Note 12)		13		15		20	ns
t _{WEZ}	Output disable time after \overline{WE} low (Note 12)		13		15		20	ns
t _{OFF}	Output disable time after CAS high (Note 12,13)		13		15		20	ns
t _{REZ}	Output disable time after \overline{RAS} high (Note 12,13)		13		15		20	ns

Note 6: An initial pause of 500μs is required after power-up followed by a minimum of eight initialization cycles (any combination of cycles containing a \overline{RAS} clock such as \overline{RAS} -Only refresh).

Note the \overline{RAS} may be cycled during the initial pause. And any 8 \overline{RAS} or $\overline{RAS/CAS}$ cycles are required after prolonged periods (greater than 64 ms) of \overline{RAS} inactivity before proper device operation is achieved.

7: Measured with a load circuit equivalent to V_{OH}=2.4V(I_{OH}=-5mA) / V_{OL}=0.4V(I_{OL}=4.2mA) load 100pF.

The reference levels for measuring of output signal are 2.0V(V_{OH}) and 0.8V(V_{OL}).

8: Assumes that t_{RC}D ≥ t_{RC}D(max) and t_{AS}C ≥ t_{AS}C(max) and t_{CP} ≥ t_{CP}(max).

9: Assumes that t_{RC}D ≤ t_{RC}D(max) and t_{RA}D ≤ t_{RA}D(max). If t_{RC}D or t_{RA}D is greater than the maximum recommended value shown in this table, t_{RA}C will increase by amount that t_{RC}D exceeds the value shown.

10: Assumes that t_{RA}D ≥ t_{RA}D(max) and t_{AS}C ≤ t_{AS}C(max).

11: Assumes that t_{CP} ≤ t_{CP}(max) and t_{AS}C ≥ t_{AS}C(max).

12: t_{OEZ}(max), t_{WEZ}(max), t_{OFF}(max) and t_{REZ}(max) defines the time at which the output achieves the high impedance state (|I_{OUT} ≤ | ±10 μA |) and is not reference to V_{OH}(min) or V_{OL}(max).

13: Output is disabled after both \overline{RAS} and CAS go to high.

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TIMING REQUIREMENTS (For Read, Write, Read-Modify-Write ,Refresh, and EDO Mode Cycles)

(Ta=0 ~ 70°C , Vcc = 5.0V ±10%, Vss=0V, unless otherwise noted See notes 14,15)

Symbol	Parameter	Limits						Unit
		M5M416165D-5,5S		M5M416165D-6,6S		M5M416165D-7,7S		
		Min	Max	Min	Max	Min	Max	
tREF	Refresh cycle time		64		64		64	ms
tREF *	Refresh cycle time		128		128		128	ms
tRP	RAS high pulse width	30		40		50		ns
tRCD	Delay time, RAS low to CAS low (Note16)	18	37	20	45	20	50	ns
tCRP	Delay time, CAS high to RAS low	5		5		5		ns
tRPC	Delay time, RAS high to CAS low	0		0		0		ns
tCPN	CAS high pulse width	8		10		13		ns
tRAD	Column address delay time from RAS low (Note17)	13	25	15	30	15	35	ns
tASR	Row address setup time before RAS low	0		0		0		ns
tASC	Column address setup time before CAS low (Note18)	0	10	0	13	0	13	ns
tRAH	Row address hold time after RAS low	8		10		10		ns
tCAH	Column address hold time after CAS low	8		10		10		ns
tDZC	Delay time, data to CAS low (Note19)	0		0		0		ns
tDZO	Delay time, data to OE low (Note19)	0		0		0		ns
tRDD	Delay time, RAS high to data (Note20)	13		15		20		ns
tCDD	Delay time, CAS high to data (Note20)	13		15		20		ns
tODD	Delay time, OE high to data (Note20)	13		15		20		ns
tWED	Delay time, W low to data (Note20)	13		15		20		ns
tT	Transition time (Note21)	1	50	1	50	1	50	ns

* : Applicable to self refresh version (M5M416165DXX-5S,-6S,-7S:option) only

Note 14: The timing requirements are assumed tT = 2ns.

15: VIH(min) and VIL(max) are reference levels for measuring timing of input signals.

16: tRCD(max) is specified as a reference point only. If tRCD is less than tRCD(max), access time is tRAC. If tRCD is greater than tRCD(max), access time is controlled exclusively by tCAC or tAA.

17: tRAD(max) is specified as a reference point only. If tRAD ≥ tRAD(max) and tASC ≤ tASC(max), access time is controlled exclusively by tAA.

18: tASC(max) is specified as a reference point only. If tRCD ≥ tRCD(max) and tASC ≥ tASC(max), access time is controlled exclusively by tCAC.

19: Either tDZC or tDZO must be satisfied.

20: Either tRDD or tCDD or tODD or tWED must be satisfied.

21: tT is measured between VIH(min) and VIL(max).

Read and Refresh Cycles

Symbol	Parameter	Limits						Unit
		M5M416165D-5,5S		M5M416165D-6,6S		M5M416165D-7,7S		
		Min	Max	Min	Max	Min	Max	
tRC	Read cycle time	90		110		130		ns
tRAS	RAS low pulse width	50	10000	60	10000	70	10000	ns
tCAS	CAS low pulse width	8	10000	10	10000	13	10000	ns
tCSH	CAS hold time after RAS low	40		48		55		ns
tRSH	RAS hold time after CAS low	13		15		20		ns
tRCS	Read Setup time before CAS low	0		0		0		ns
tRCH	Read hold time after CAS high (Note 22)	0		0		0		ns
tRRH	Read hold time after RAS high (Note 22)	10		10		10		ns
tRAL	Column address to RAS hold time	25		30		35		ns
tCAL	Column address to CAS hold time	15		18		20		ns
tORH	RAS hold time after OE low	13		15		20		ns
tOCH	CAS hold time after OE low	13		15		20		ns

Note 22: Either tRCH or tRRH must be satisfied for a read cycle.

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Write Cycle (Early Write and Delayed Write)

Symbol	Parameter	Limits						Unit
		M5M416165D-5,5S		M5M416165D-6,6S		M5M416165D-7,7S		
		Min	Max	Min	Max	Min	Max	
t _{WC}	Write cycle time	90		110		130		ns
t _{RAS}	RAS low pulse width	50	10000	60	10000	70	10000	ns
t _{CAS}	CAS low pulse width	8	10000	10	10000	13	10000	ns
t _{CSH}	CAS hold time after RAS low	40		48		55		ns
t _{RSH}	RAS hold time after CAS low	13		15		20		ns
t _{WCS}	Write setup time before CAS low (Note 24)	0		0		0		ns
t _{WCH}	Write hold time after CAS low	8		10		13		ns
t _{CWL}	CAS hold time after W low	8		10		13		ns
t _{RWL}	RAS hold time after W low	8		10		13		ns
t _{WP}	Write pulse width	8		10		13		ns
t _{DS}	Data setup time before CAS low or W low	0		0		0		ns
t _{DH}	Data hold time after CAS low or W low	8		10		13		ns

Read-Write and Read-Modify-Write Cycles

Symbol	Parameter	Limits						Unit
		M5M416165D-5,5S		M5M416165D-6,6S		M5M416165D-7,7S		
		Min	Max	Min	Max	Min	Max	
t _{RWC}	Read write/read modify write cycle time (Note23)	109		133		161		ns
t _{RAS}	RAS low pulse width	75	10000	89	10000	107	10000	ns
t _{CAS}	CAS low pulse width	38	10000	44	10000	57	10000	ns
t _{CSH}	CAS hold time after RAS low	70		82		99		ns
t _{RSH}	RAS hold time after CAS low	38		44		57		ns
t _{RCS}	Read setup time before CAS low	0		0		0		ns
t _{CWD}	Delay time, CAS low to W low (Note24)	28		32		42		ns
t _{RWD}	Delay time, RAS low to W low (Note24)	65		77		92		ns
t _{AWD}	Delay time, address to W low (Note24)	40		47		57		ns
t _{OEH}	OE hold time after W low	13		15		20		ns

Note 23: t_{RWC} is specified as t_{RWC(min)}=t_{RAC(max)}+t_{ODD(min)}+t_{RWL(min)}+t_{RP(min)}+4t.

24: t_{WCS}, t_{CWD}, t_{RWD} and t_{AWD} are specified as reference points only. If t_{WCS} ≥ t_{WCS(min)} the cycle is an early write cycle and the DQ pins will remain high impedance throughout the entire cycle. If t_{CWD} ≥ t_{CWD(min)}, t_{RWD} ≥ t_{RWD(min)}, t_{AWD} ≥ t_{AWD(min)} and t_{CPWD} ≥ t_{CPWD(min)} (for EDO mode cycle only), the cycle is a read-modify-write cycle and the DQ will contain the data read from the selected address. If neither of the above condition (delayed write) of the DQ (at access time and until CAS or OE goes back to V_{IH}) is indeterminate.

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EDO Mode Cycle (Read, Early Write, Read-Write, Read-Modify-Write Cycle,
, Read Write Mix Cycle, Hi-Z control by \overline{OE} or \overline{W}) (Note 25)

Symbol	Parameter	Limits						Unit
		M5M416165D-5,5S		M5M416165D-6,6S		M5M416165D-7,7S		
		Min	Max	Min	Max	Min	Max	
tHPC	EDO mode read/write cycle time (Note26)	20		25		30		ns
tHPRWC	EDO mode read write / read modify write cycle time	57		66		79		ns
tDOH	Output hold time from \overline{CAS} low	5		5		5		ns
tRAS	RAS low pulse width for read write cycle (Note27)	65	100000	77	100000	92	100000	ns
tCP	CAS high pulse width (Note28)	8	13	10	16	10	16	ns
tCPRH	RAS hold time after \overline{CAS} precharge	30		35		40		ns
tCPWD	Delay time, \overline{CAS} precharge to \overline{W} low (Note24)	45		52		62		ns
tCHOL	Hold time to maintain the data Hi-Z until CAS access	7		7		7		ns
tOEPE	\overline{OE} Pulse Width (Hi-Z control)	7		7		7		ns
tWPE	\overline{W} Pulse Width (Hi-Z control)	7		7		7		ns
tHCWD	Delay time, \overline{CAS} low to \overline{W} low after read	28		32		42		ns
tHAWD	Delay time, Address to \overline{W} low after read	52		62		72		ns
tHPWD	Delay time, \overline{CAS} precharge to \overline{W} low after read	62		72		82		ns
tHCOD	Delay time, \overline{CAS} low to \overline{OE} high after read	13		15		20		ns
tHAOD	Delay time, Address to \overline{OE} high after read	25		30		35		ns
tHPOD	Delay time, \overline{CAS} precharge to \overline{OE} high after read	30		35		40		ns

Note 25: All previously specified timing requirements and switching characteristics are applicable to their respective EDO mode cycle.

26: tHPC(min) is specified in the case of read-only and early write-only in EDO mode.

27: tRAS(min) is specified as two cycles of \overline{CAS} input are performed.

28: tCP(max) is specified as a reference point only.

\overline{CAS} before \overline{RAS} Refresh Cycle (Note 29)

Symbol	Parameter	Limits						Unit
		M5M416165D-5,-5S		M5M416165D-6,-6S		M5M416165D-7,-7S		
		Min	Max	Min	Max	Min	Max	
tCSR	\overline{CAS} setup time before \overline{RAS} low	5		5		5		ns
tCHR	\overline{CAS} hold time after \overline{RAS} low	10		10		15		ns
tCAS	\overline{CAS} low pulse width	17		17		22		ns

Note 29: Eight or more \overline{CAS} before \overline{RAS} cycles instead of eight \overline{RAS} cycles are necessary for proper operation of \overline{CAS} before \overline{RAS} refresh mode.

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SELF REFRESH SPECIFICATIONS

Self refresh devices are denoted by "S" after speed item, like -5S / -6S / -7S. The other characteristics and requirements than the below are same as normal devices.

TIMING REQUIREMENTS (Ta=0 ~ 70°C, Vcc=5.0V±10%, Vss=0V, unless otherwise noted See notes 14,15)

Symbol	Parameter	Limits						Unit
		M5M416165D-5S		M5M416165D-6S		M5M416165D-7S		
		Min	Max	Min	Max	Min	Max	
t _{RASS}	Self Refresh RAS low pulse width	100		100		100		μs
t _{RPS}	Self Refresh RAS high precharge time	90		110		130		ns
t _{CHS}	Self Refresh RAS hold time	- 50		- 50		- 50		ns
t _{RSR}	Read setup time before RAS low	10		10		10		ns
t _{RHR}	Read hold time after RAS low	10		10		15		ns

Note 14: The timing requirements are assumed $t_T = 2ns$.

15: $V_{IH(min)}$ and $V_{IL(max)}$ are reference levels for measuring timing of input signals.

SELF REFRESH ENTRY & EXIT CONDITIONS

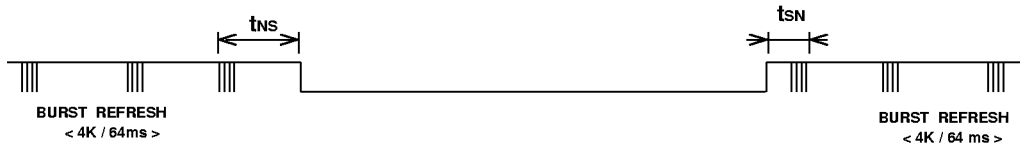
(1) In case of distributed refresh

The last / first full refresh cycles (1K) must be made within t_{NS} / t_{SN} before / after self refresh , on the condition of $t_{NS} \leq 64 \text{ ms}$ and $t_{SN} \leq 64 \text{ ms}$.



(2) In case of burst refresh

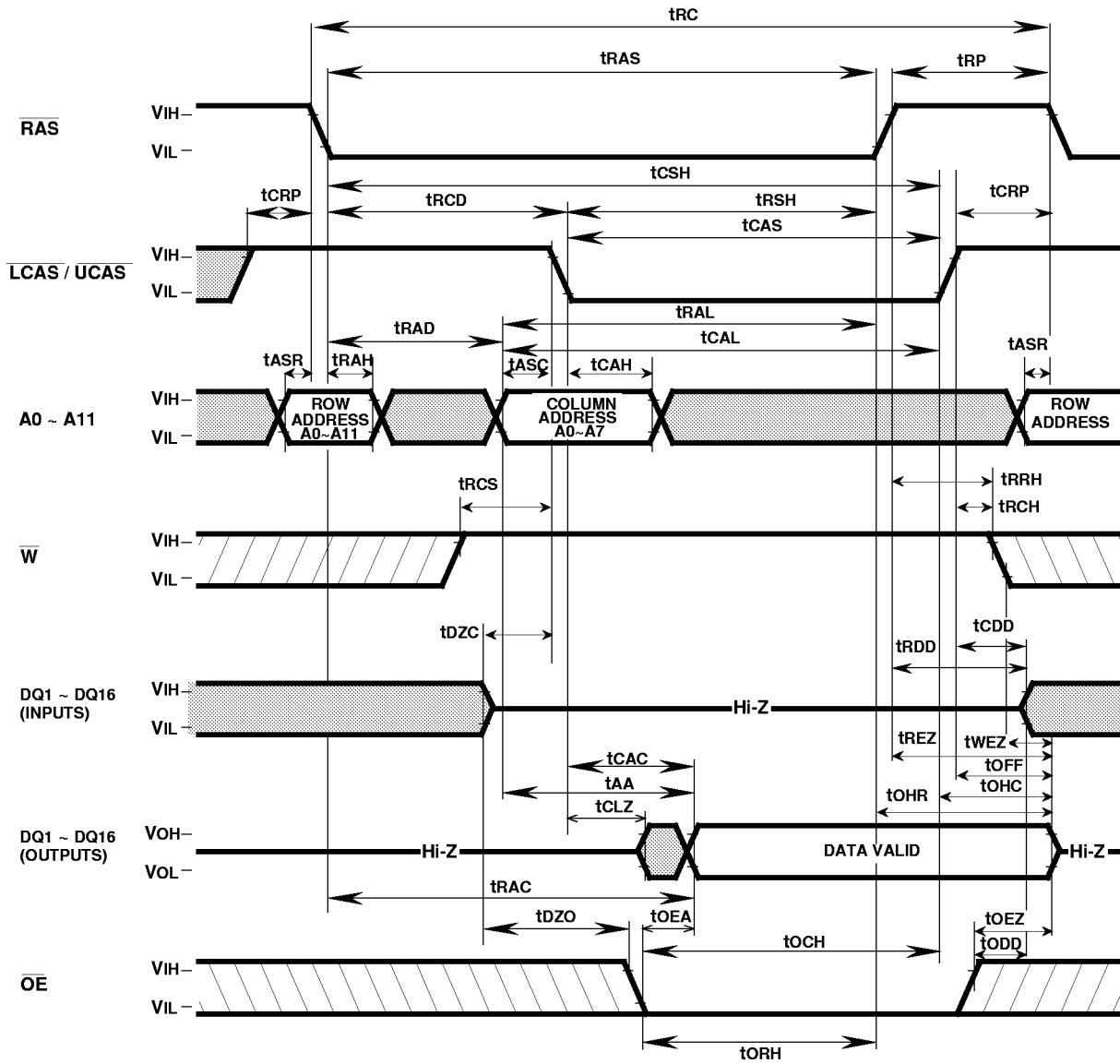
The last / first full refresh cycles (1K) must be made within t_{NS} / t_{SN} before / after self refresh , on the condition of $t_{NS} + t_{SN} \leq 64 \text{ ms}$.





M5M416165DJ, TP-5, -5S, -6, -6S, -7, -7S

EDO (HYPER PAGE) MODE 1677216-BIT (1048576-WORD BY 16-BIT) DYNAMIC RAM

Timing Diagrams (Note 30) Read Cycle



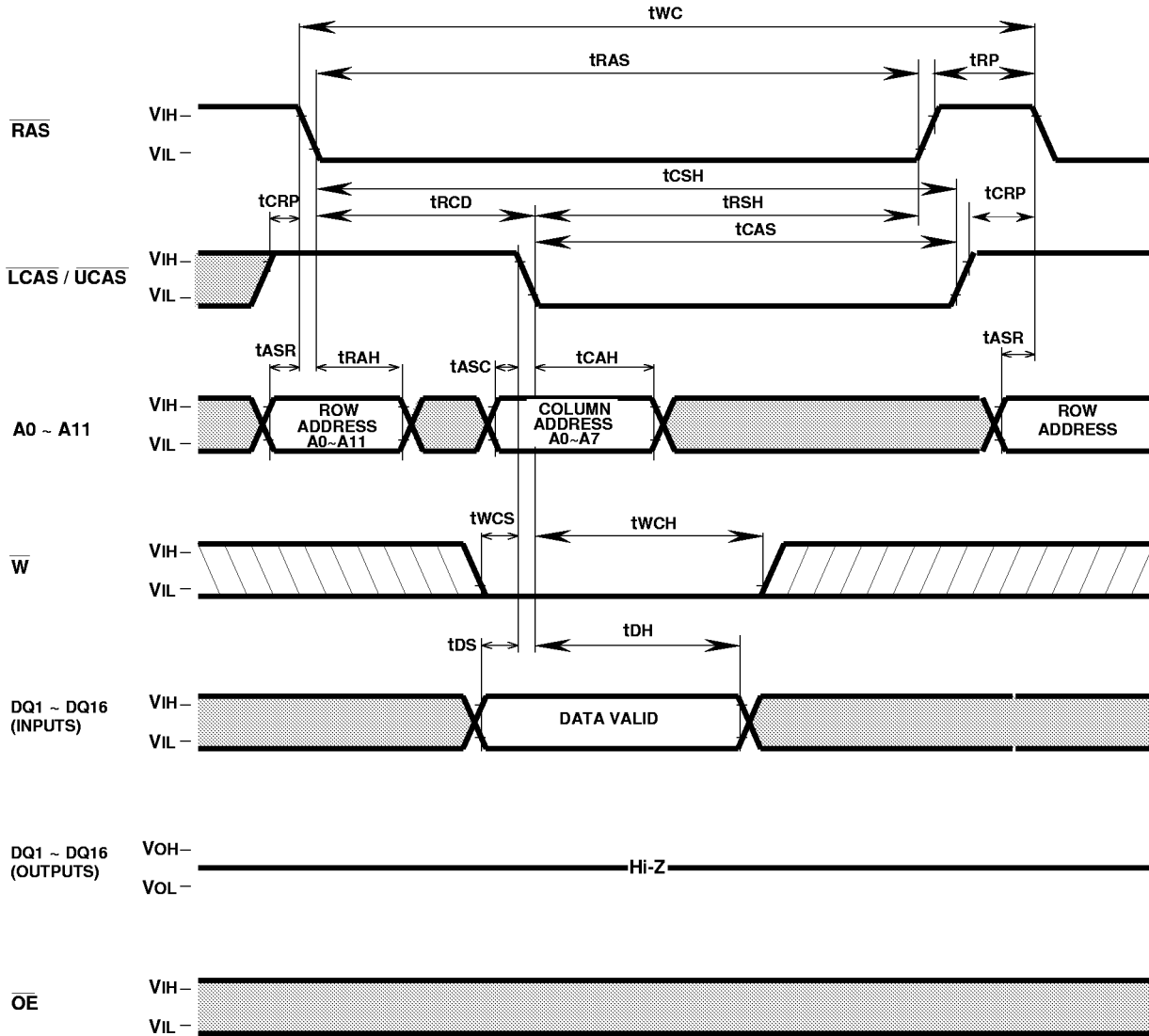
Note 30  Indicates the don't care input.
 $V_{IH(min)} \leq V_{IN} \leq V_{IH(max)}$ or $V_{IL(min)} \leq V_{IN} \leq V_{IL(max)}$

 Indicates the invalid output.

M5M416165DJ, TP-5, -5S, -6, -6S, -7, -7S

EDO (HYPER PAGE) MODE 1677216-BIT (1048576-WORD BY 16-BIT) DYNAMIC RAM

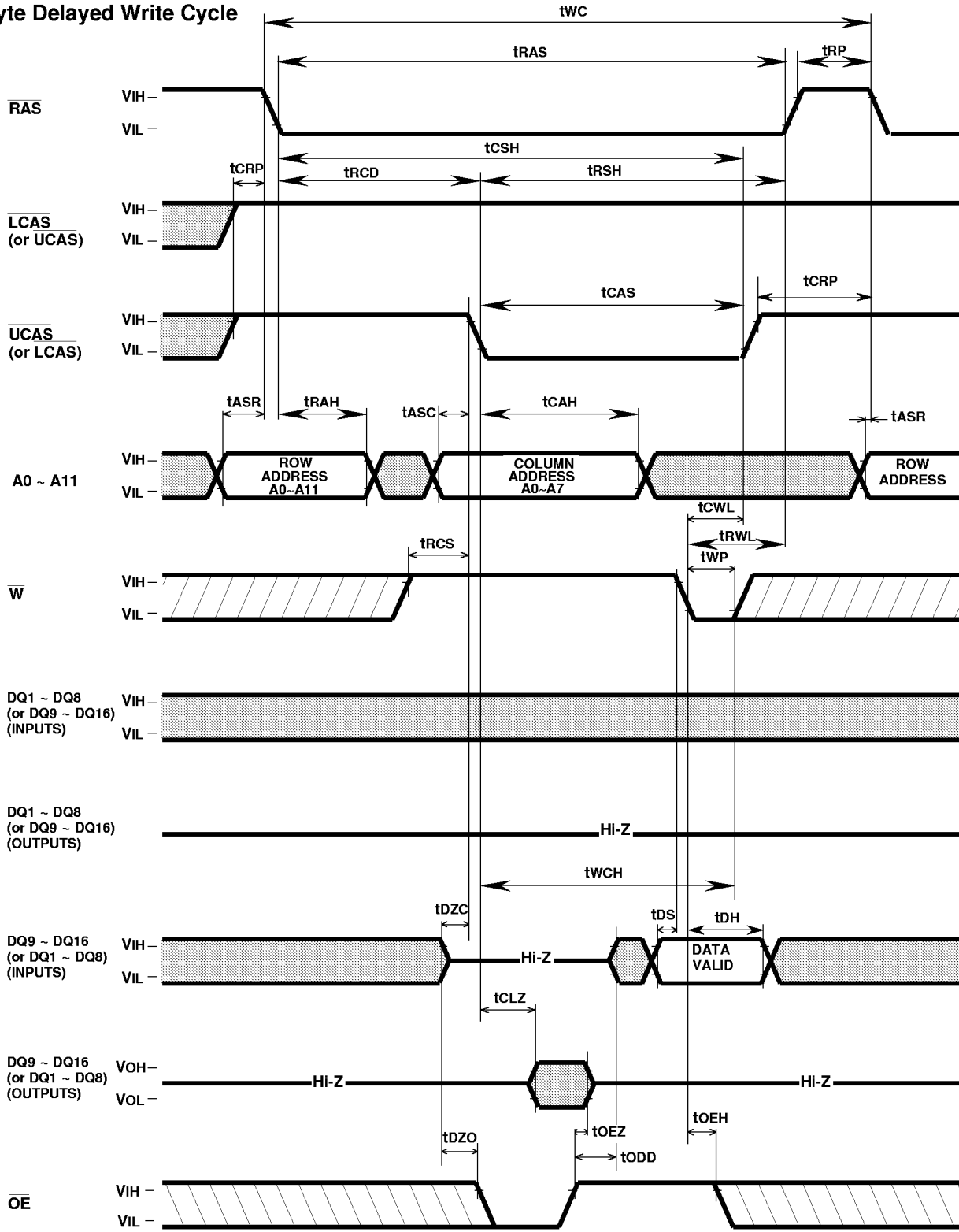
Early Write Cycle



M5M416165DJ, TP-5, -5S, -6, -6S, -7, -7S

EDO (HYPER PAGE) MODE 1677216-BIT (1048576-WORD BY 16-BIT) DYNAMIC RAM

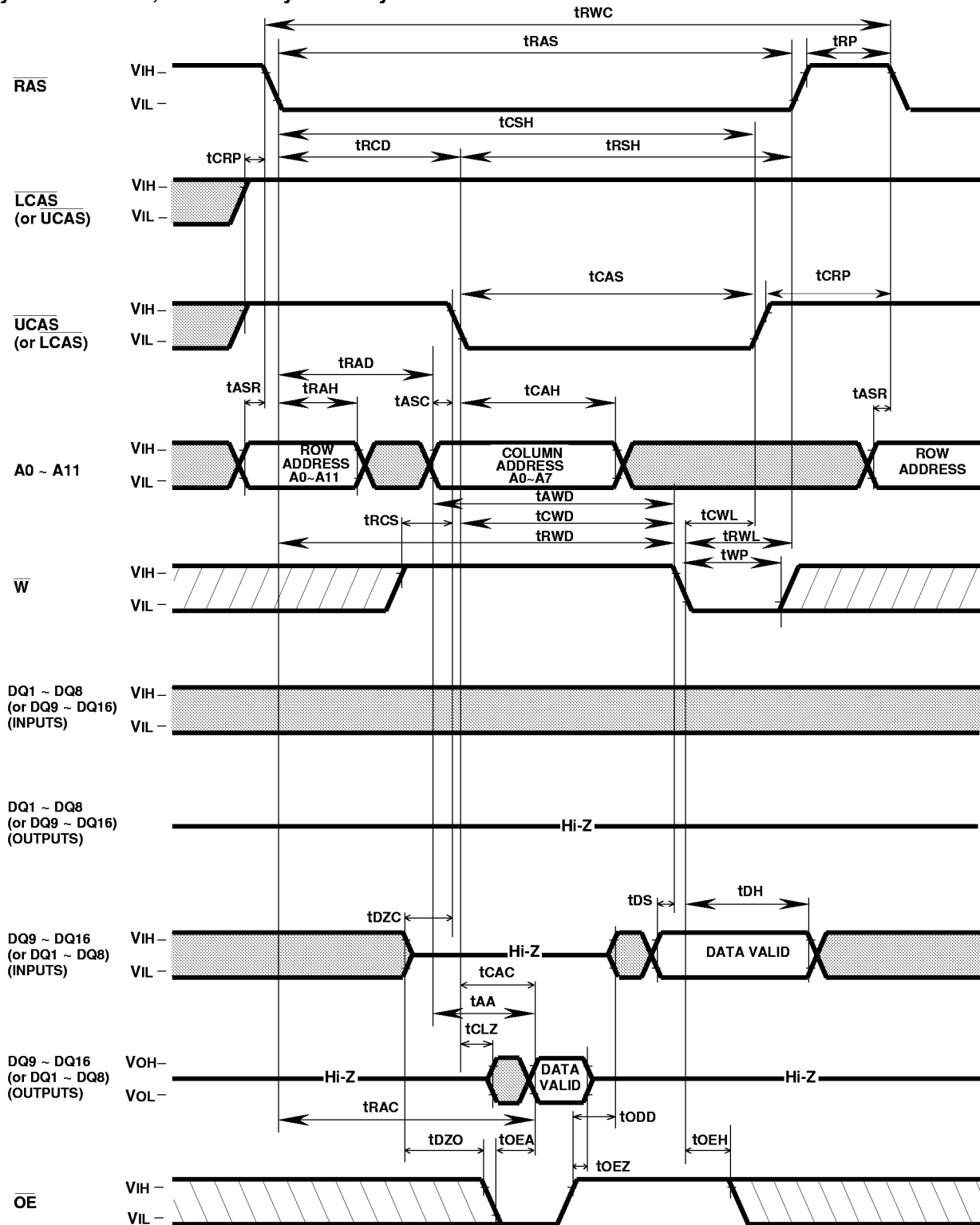
Byte Delayed Write Cycle



M5M416165DJ, TP-5, -5S, -6, -6S, -7, -7S

EDO (HYPER PAGE) MODE 16777216-BIT (1048576-WORD BY 16-BIT) DYNAMIC RAM

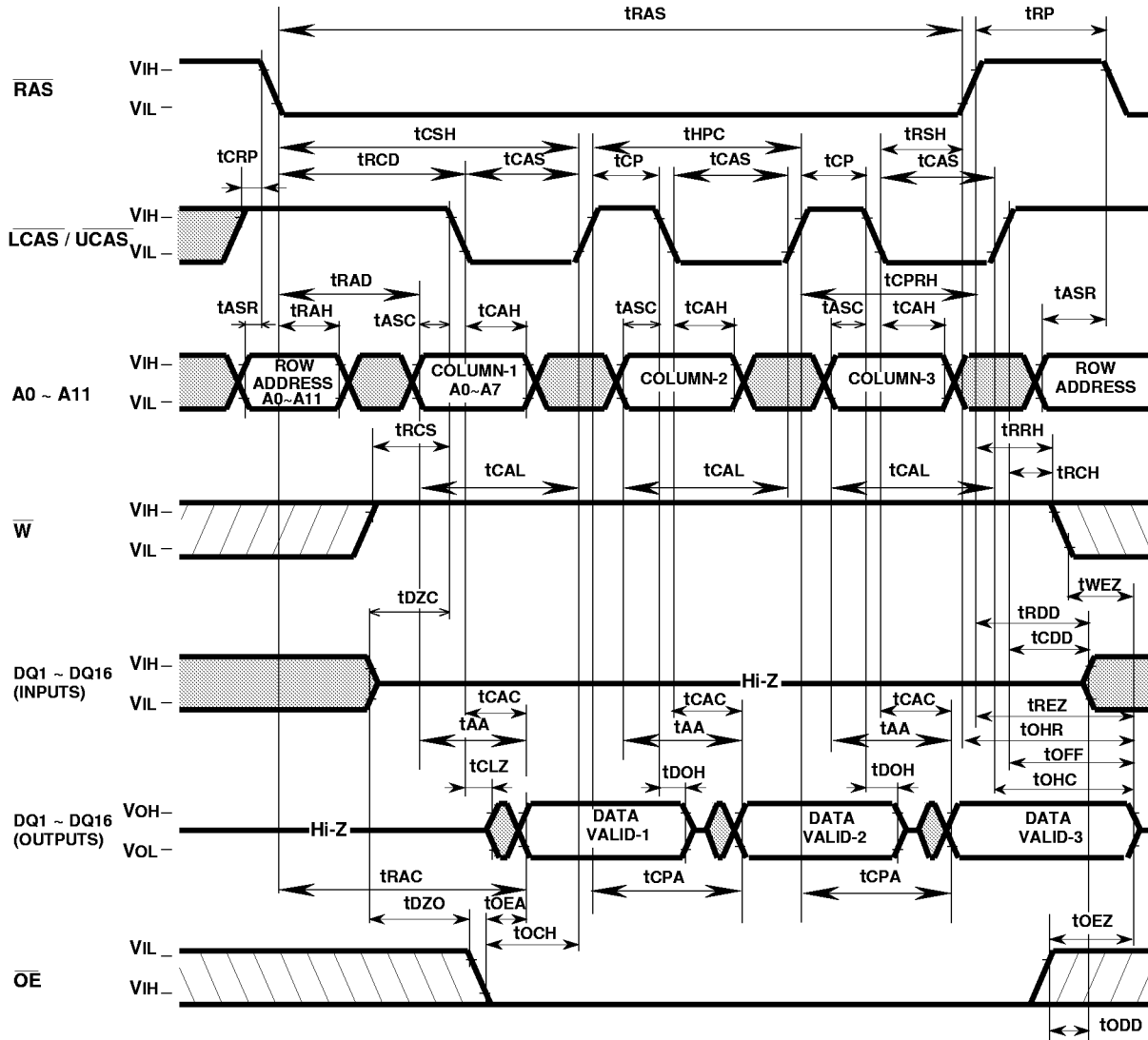
Byte Read-Write, Read-Modify-Write Cycle



M5M416165DJ, TP-5, -5S, -6, -6S, -7, -7S

EDO (HYPER PAGE) MODE 16777216-BIT (1048576-WORD BY 16-BIT) DYNAMIC RAM

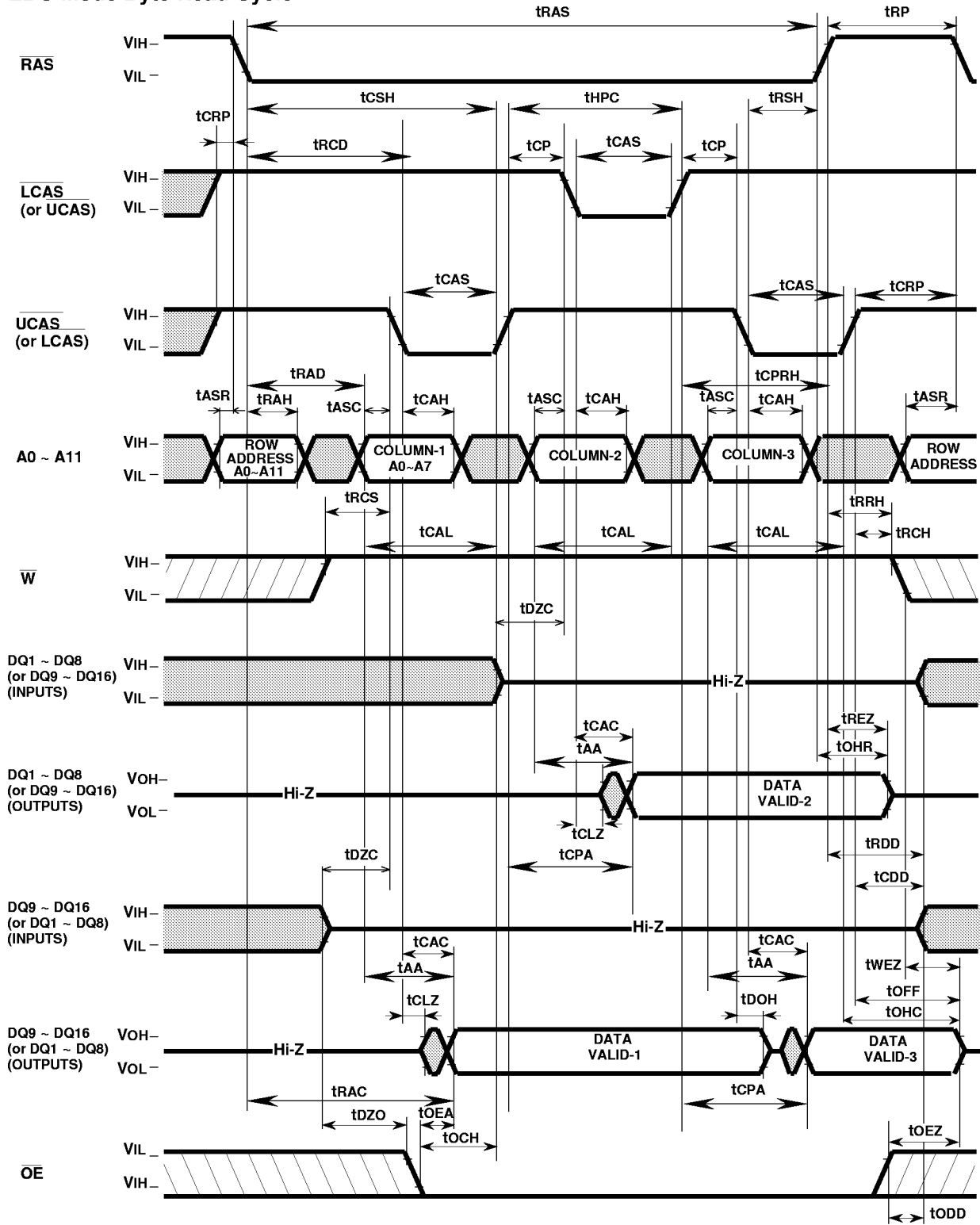
EDO Mode Read Cycle



M5M416165DJ, TP-5, -5S, -6, -6S, -7, -7S

EDO (HYPER PAGE) MODE 1677216-BIT (1048576-WORD BY 16-BIT) DYNAMIC RAM

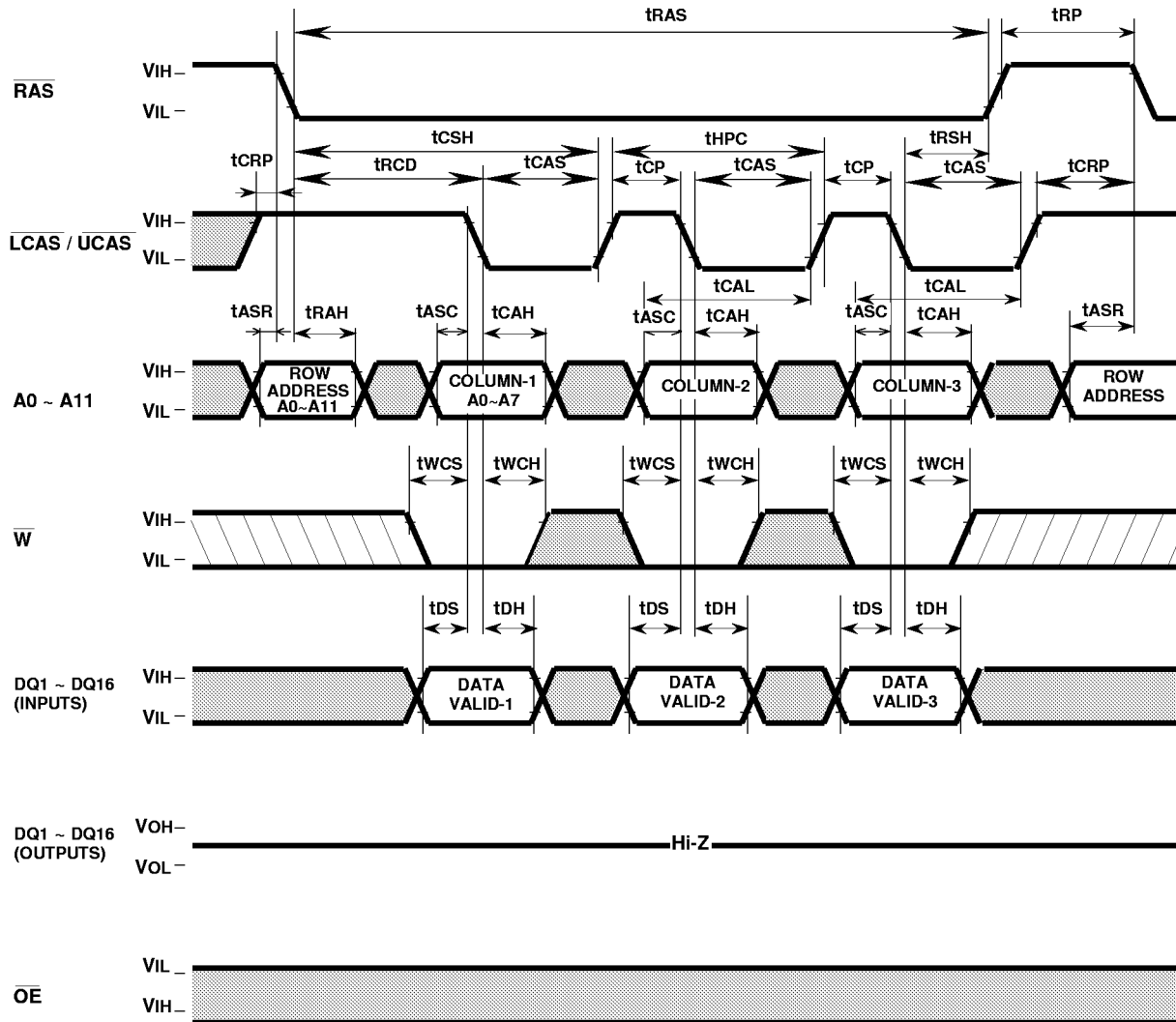
EDO Mode Byte Read Cycle



M5M416165DJ, TP-5, -5S, -6, -6S, -7, -7S

EDO (HYPER PAGE) MODE 1677216-BIT (1048576-WORD BY 16-BIT) DYNAMIC RAM

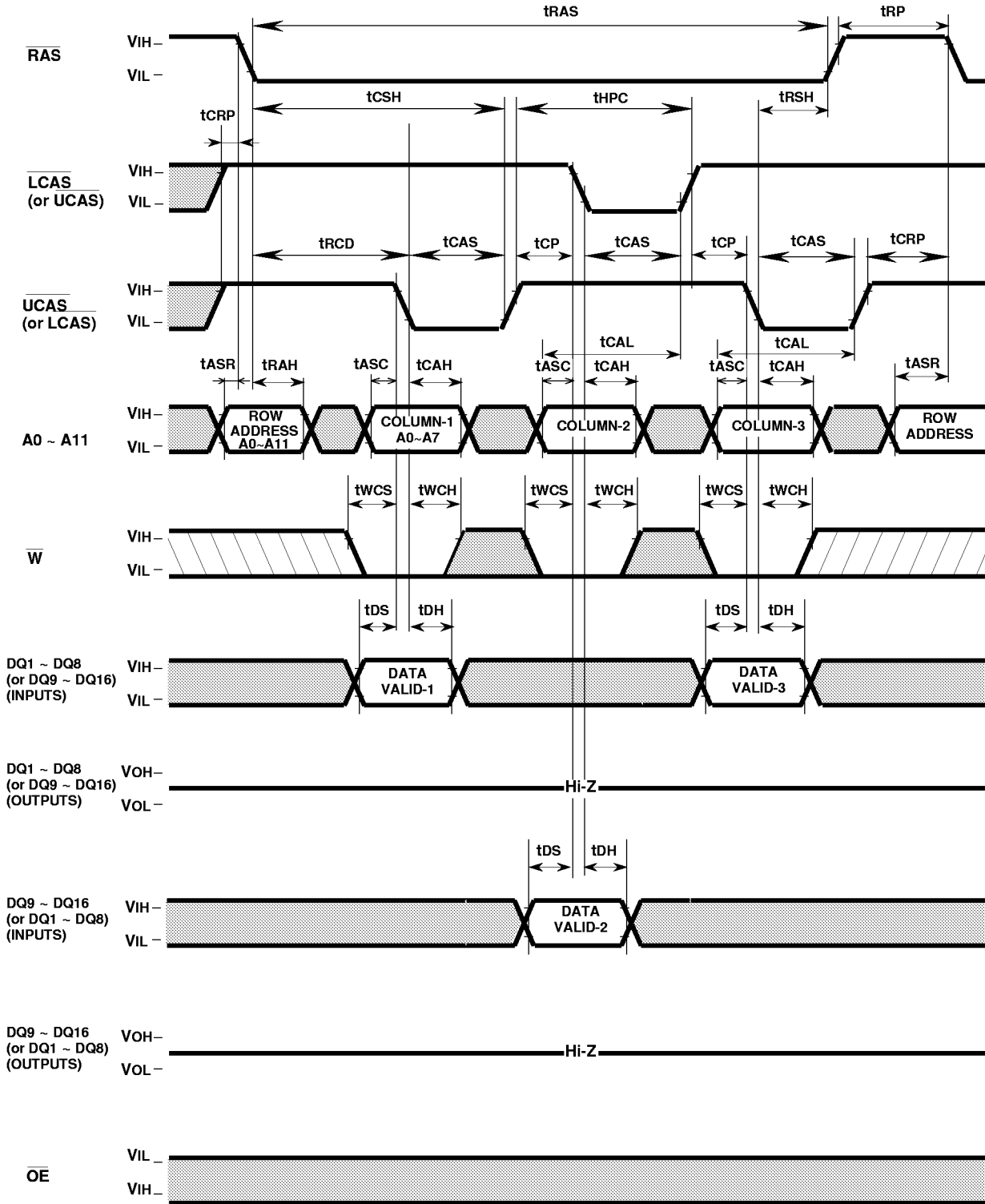
EDO Mode Early Write Cycle



M5M416165DJ, TP-5, -5S, -6, -6S, -7, -7S

EDO (HYPER PAGE) MODE 1677216-BIT (1048576-WORD BY 16-BIT) DYNAMIC RAM

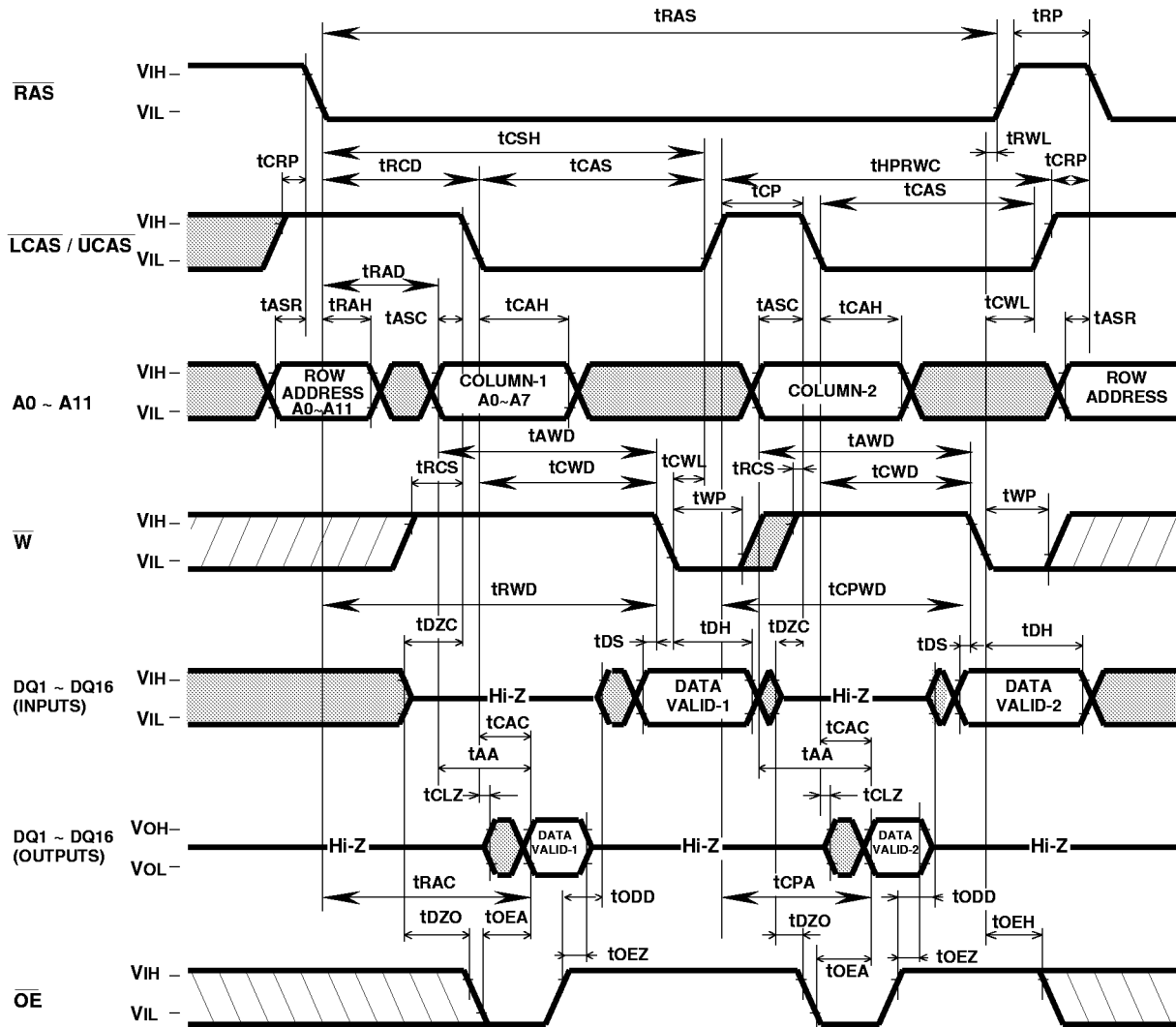
EDO Mode Byte Early Write Cycle



M5M416165DJ, TP-5, -5S, -6, -6S, -7, -7S

EDO (HYPER PAGE) MODE 1677216-BIT (1048576-WORD BY 16-BIT) DYNAMIC RAM

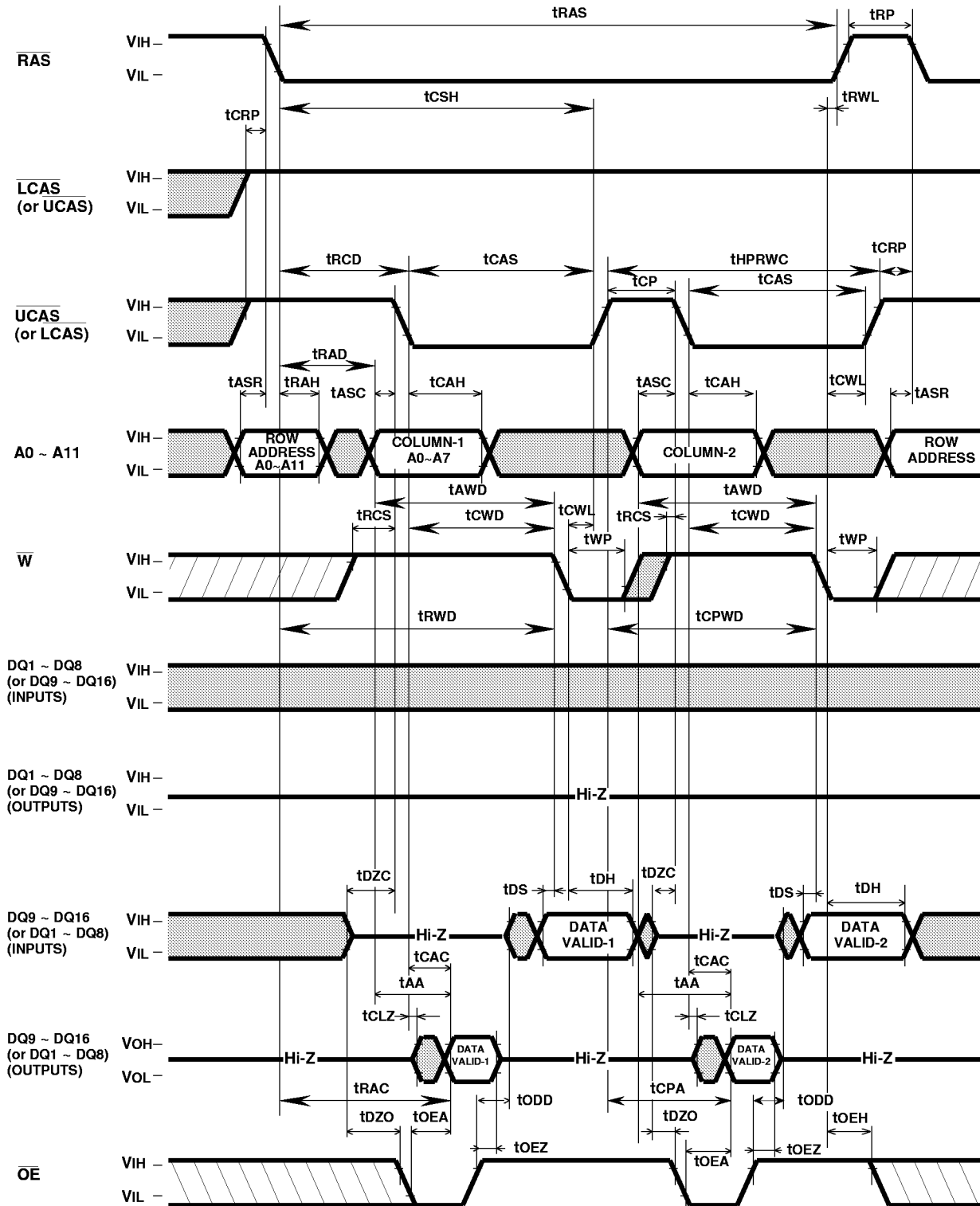
EDO Mode Read-Write, Read-Modify-Write Cycle



M5M416165DJ, TP-5, -5S, -6, -6S, -7, -7S

EDO (HYPER PAGE) MODE 1677216-BIT (1048576-WORD BY 16-BIT) DYNAMIC RAM

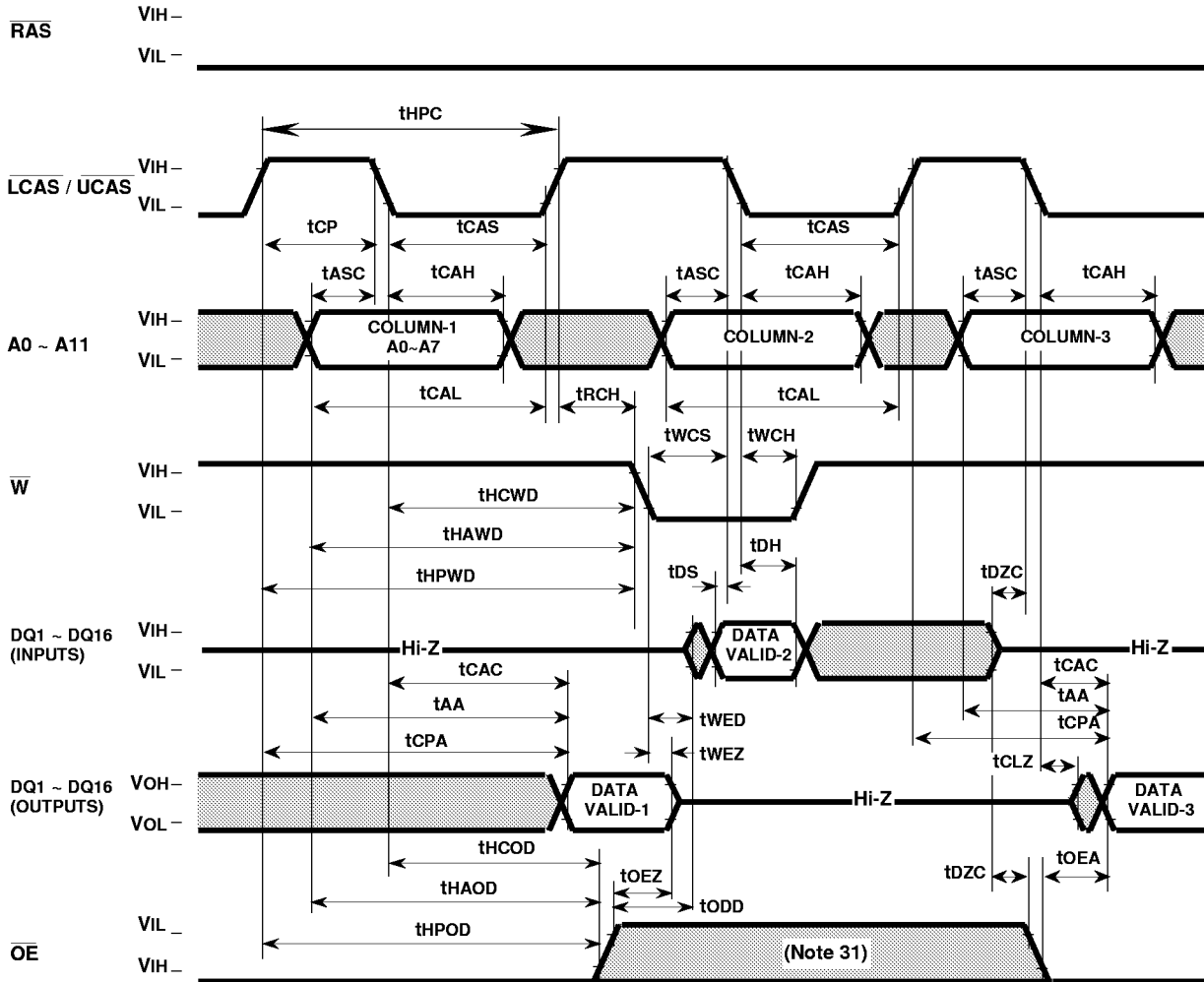
EDO Mode Byte Read-Write, Read-Modify-Write Cycle



M5M416165DJ, TP-5, -5S, -6, -6S, -7, -7S

EDO (HYPER PAGE) MODE 16777216-BIT (1048576-WORD BY 16-BIT) DYNAMIC RAM

EDO Mode Mix Cycle (2) (Note 31)

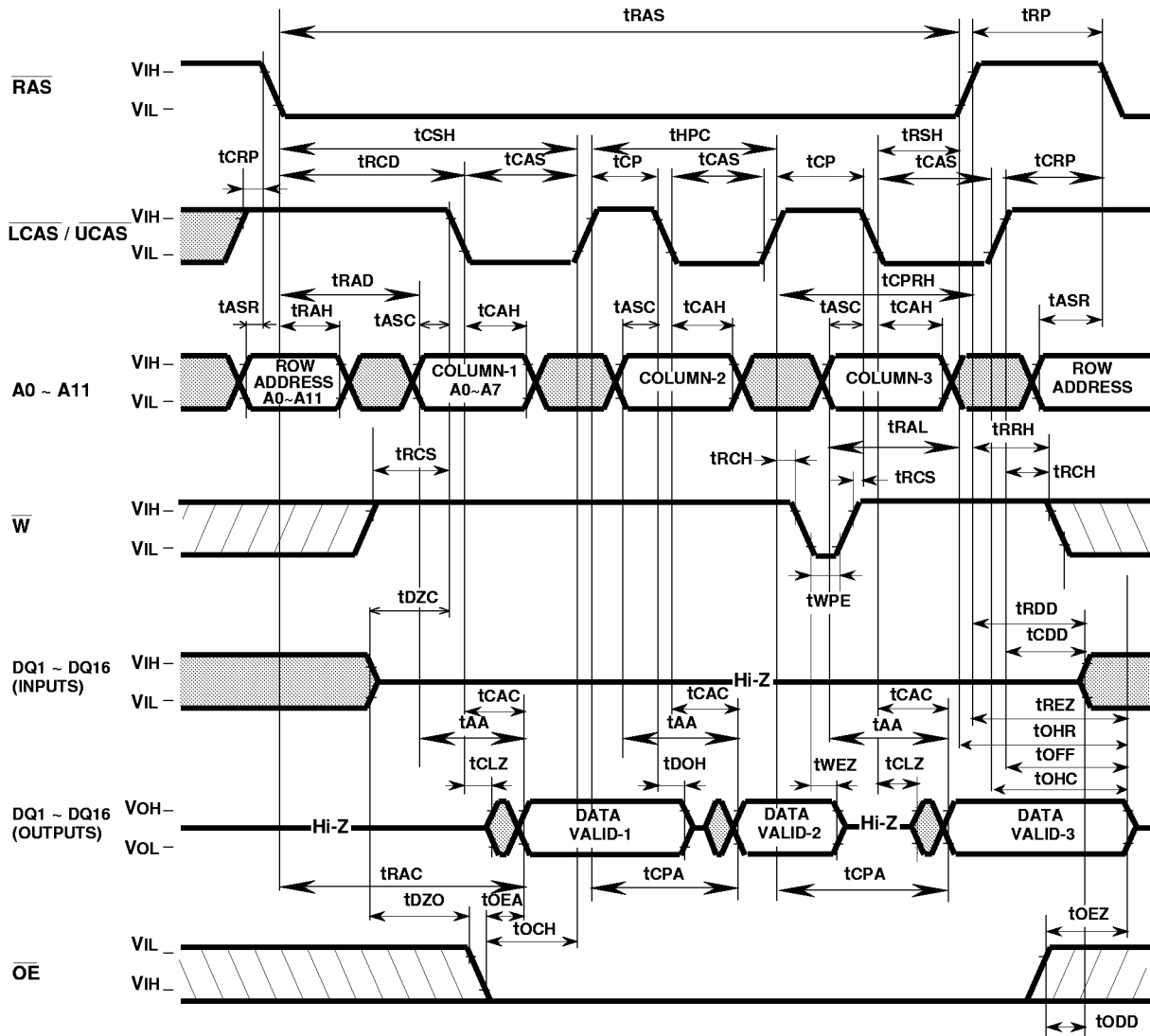


(Note 31: $\overline{OE} = L$; \overline{W} Hi-Z control
 $OE = H$; OE Hi-Z control)

M5M416165DJ, TP-5, -5S, -6, -6S, -7, -7S

EDO (HYPER PAGE) MODE 16777216-BIT (1048576-WORD BY 16-BIT) DYNAMIC RAM

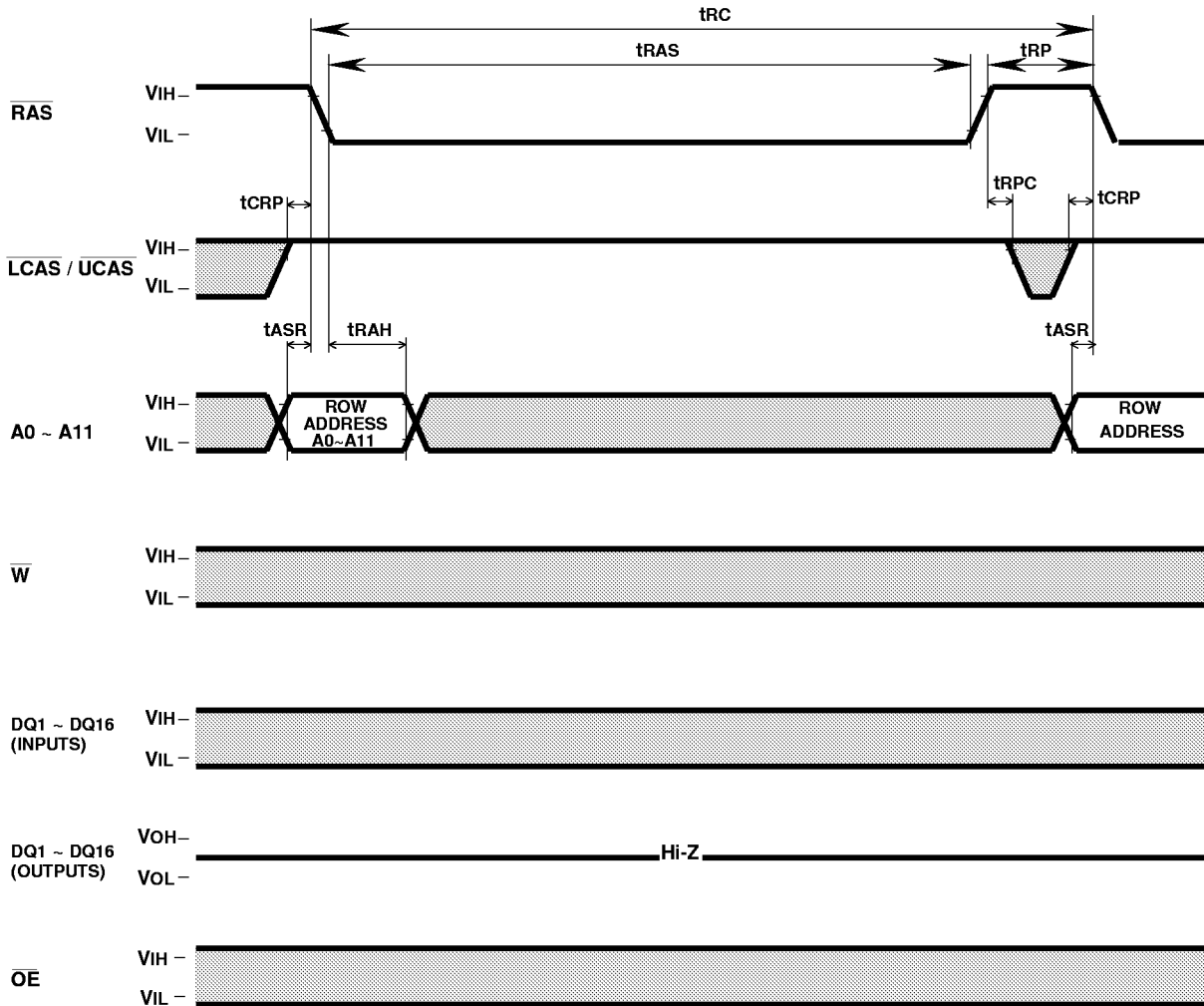
EDO Mode Read Cycle (Hi-Z control by \overline{W})



M5M416165DJ, TP-5, -5S, -6, -6S, -7, -7S

EDO (HYPER PAGE) MODE 1677216-BIT (1048576-WORD BY 16-BIT) DYNAMIC RAM

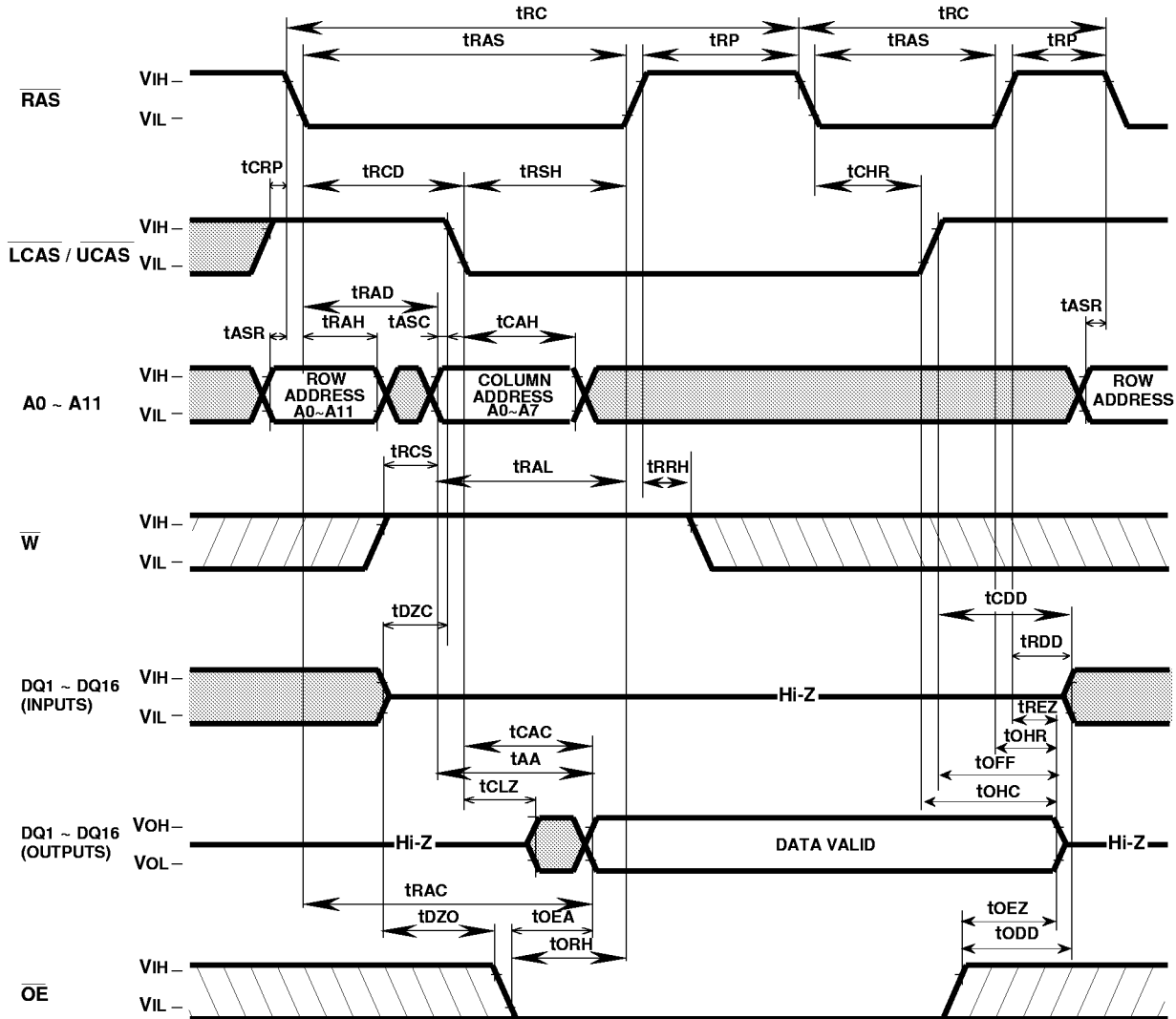
RAS-only Refresh Cycle



M5M416165DJ, TP-5, -5S, -6, -6S, -7, -7S

EDO (HYPER PAGE) MODE 1677216-BIT (1048576-WORD BY 16-BIT) DYNAMIC RAM

Hidden Refresh Cycle (Read) (Note 32)

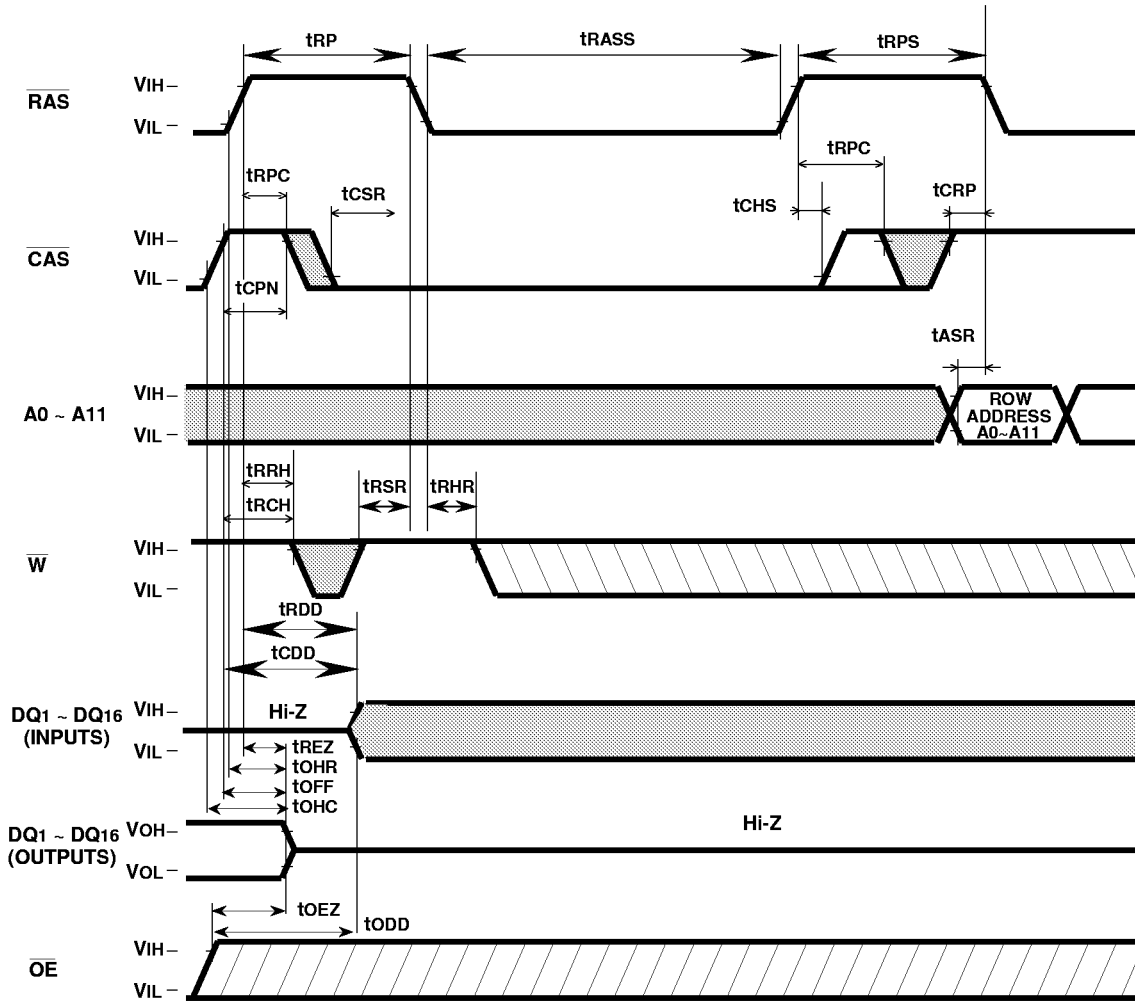


Note 32: Early write, delayed write, read write or read modify write cycle is applicable instead of read cycle. Timing requirements and output state are the same as that of each cycle shown above.

M5M416165DJ, TP-5, -5S, -6, -6S, -7, -7S

EDO (HYPER PAGE) MODE 1677216-BIT (1048576-WORD BY 16-BIT) DYNAMIC RAM

Self Refresh Cycle *

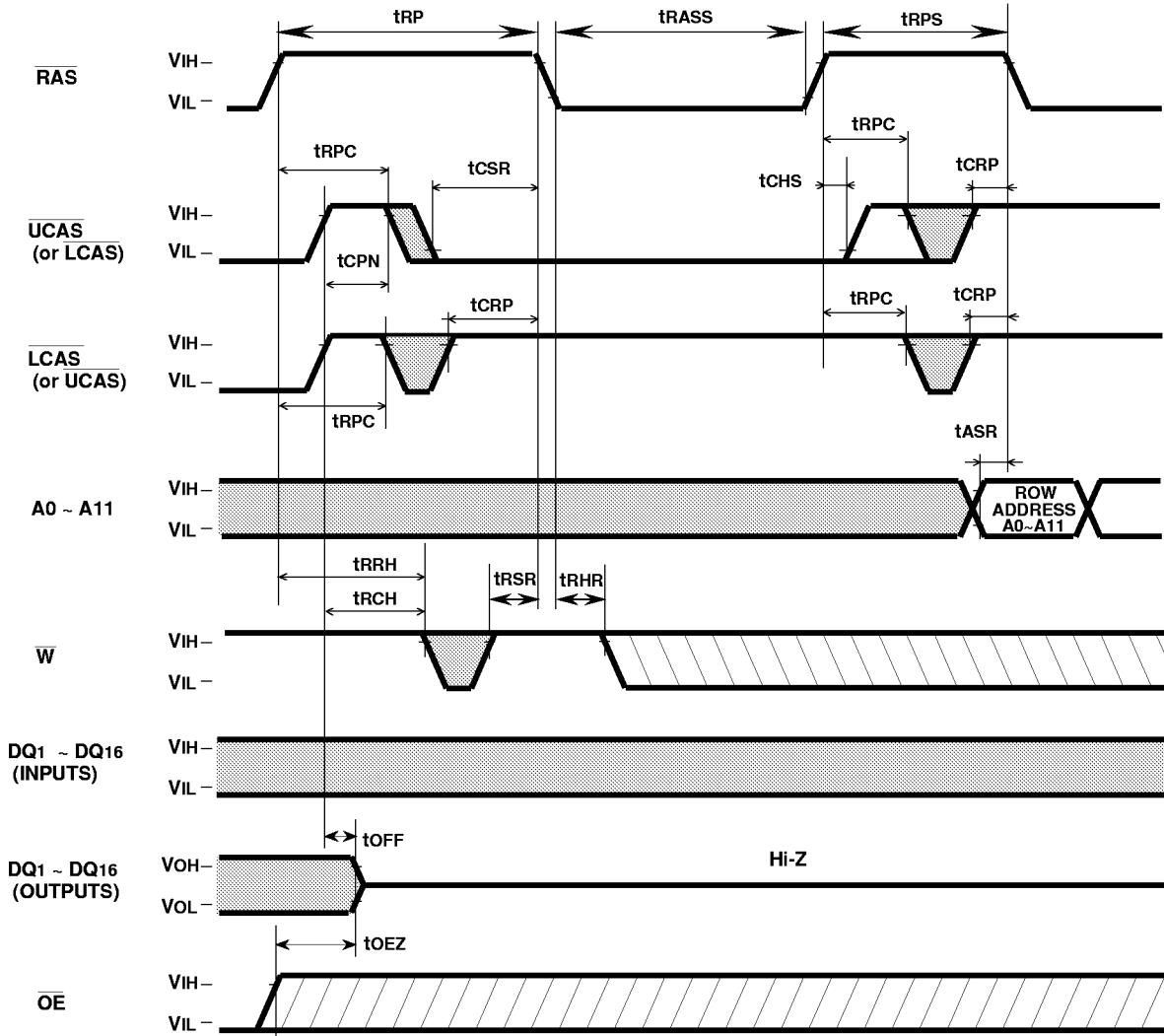


* :Applicable to self refresh version (M5M416165Dxx-5s,-6s,-7s : option) only

M5M416165DJ, TP-5, -5S, -6, -6S, -7, -7S

EDO (HYPER PAGE) MODE 1677216-BIT (1048576-WORD BY 16-BIT) DYNAMIC RAM

Upper (Lower) Self Refresh Cycle *



* :Applicable to self refresh version (M5M416165Dxx-5s,-6s,-7s : option) only